

# ABSTRACT OF THE DISCLOSURE

A packaging assembly includes a substrate; chip-site lands disposed on the first surface; first solder balls  
5 connected to the chip-site lands; second solder balls connected to the first solder balls including solder materials having higher melting temperatures than the first solder balls; a semiconductor chip having a plurality of bonding pads connected to the second solder balls on  
10 a surface of the semiconductor chip; and an underfill resin disposed around the first and second solder balls.